

Amendments to the Abstract:

Please replace the Abstract at page 20 of the specification with the following amended paragraph:

ABSTRACT OF THE DISCLOSURE

A ~~system and~~ method for cleaning and drying semiconductor wafers improves device yield by providing more advanced control of the ratio of drying fluid to cleaning fluid, for example the ratio of N₂ vapor to IPA vapor. In addition, a quick drain process is employed to improve process throughput, and to further improve particle and watermark removal during the cleaning and drying steps.